

# Semiconductor Fabtech Editorial Calendar 2007/08

## **Editorial Contact**

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## **Editorial Information**

Press releases should be sent in word document format via email.

Product releases should be accompanied with photos in high-res format.

Abstracts or topic outlines should be 100 words (minimum). Full spec sheet is available on request.

Edition	FT35 September 2007	FT36 December 2007	FT37 March 2008	FT38 June 2008
Themes	Copper Focus	Industry Overview	TBA	TBA
Special features	300mm Report Bill Mc Clean – IC Insights – ‘State of the Industry’ Jim Moran, Spansion COO interview	300mm Report iSuppli Corp. – Len Jelinek – ‘State of the Industry’	300mm Report Gartner et al – ‘State of the Industry’	300mm Report
Fab Management	Productivity Improvements	Fab Automation - Qimonda ISMI Conference Review	APC	Manufacturing Efficiency Strategies
EHS	Environmental Strategies - Intel Corp.	Green Fab Initiatives - SEMATECH	Abatement Strategies	Energy Efficiency
Cleanroom	Chambers and Parts - Cleaning methodologies	ISMI Conference Review	300mm Fab Design	300mm Site Selection
Materials and Gases	High-k Materials Development – SEMATECH Slurry Performance - TBA	300mm Wafer Manufacturing  Copper Barrier Materials	SOI Developments  CMP Consumables	Strained Silicon  Low-k dielectrics
Lithography	Immersion Lithography  Line-edge Roughness	Advanced Mask Issues – IBM  Metrology Tool Focus	Anti-reflective Coatings	Double Patterning  Immersion Lithography
Wafer Processing	Advanced Interconnect Special Focus; Interconnect Scaling Challenges; ECMP Enabling Technology; Defect Monitoring	DRAM Materials and Structures for next-generation memory – IMEC et al FEOL Implant Developments – Applied Materials	Defect Inspection Focus  FEOL Process Focus	Wafer Cleaning Focus  Interconnect Metrology Focus
CC&SS	Vacuum Process Chemicals and Pump Settings - Oerlikon Leybold	RF Power	Tool Maintenance Strategies	Tool Gas Delivery Systems
Publishing – Deadline for Materials	12 <sup>th</sup> August 2007	30 <sup>th</sup> November 2007	22 <sup>nd</sup> February 2008	16 <sup>th</sup> May 2008